

ABSTRACT OF THE DISCLOSURE

1 A chip size package semiconductor device can have reliable solder mounting and
2 improved mounting reliability. A semiconductor device (10) of one embodiment can include
3 a semiconductor chip (1) mounted to a bottom portion (11) of a metal base (10). A metal
4 base (10) can have side portions (12) with connection electrodes (15) having a surface level
5 higher than that of electrodes (7 and 8) on a surface of the semiconductor chip (1) by a
6 difference (d). The semiconductor device (10) can be mounted face down without abutting
7 the semiconductor chip (1) against a mounting substrate, thereby preventing mechanical
8 damage to a semiconductor chip (1). At the same time, a solder layer can be formed in the
9 gap between electrodes (7 and 8) and the mounting substrate, thereby raising the reliability of
10 the soldering connection.